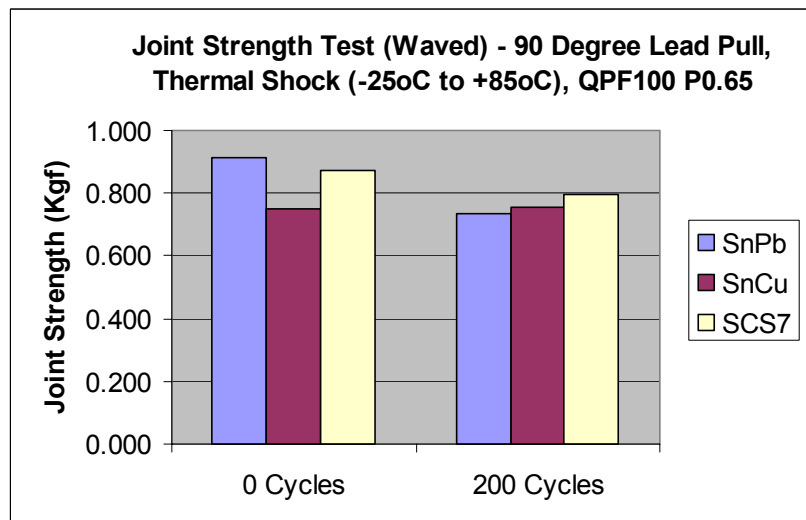


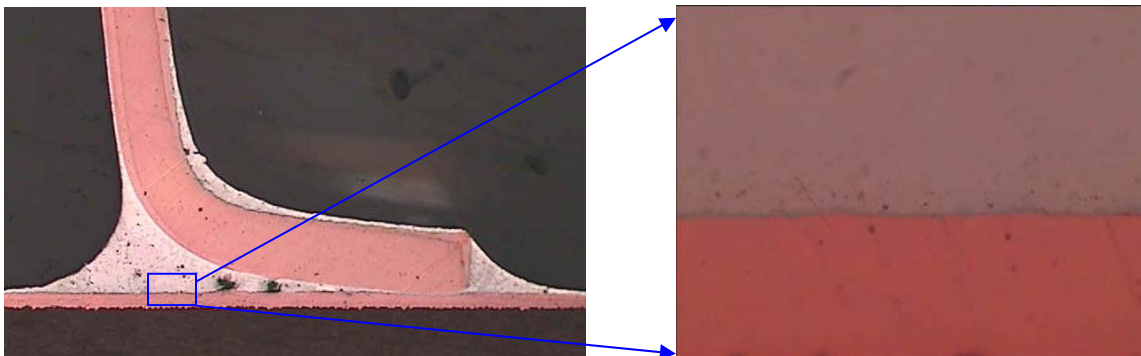
Thermal Shock Test

Condition : - 25 °C to +85 °C (Dual Air Chamber)
Component : QFP100, P0.65mm
PCB Surface : Copper, Pre-flux



Joint strength of SCS7 is significantly better than SnPb and SnCu after thermal shock test.

After 1000 Cycles Thermal Shock:



No abnormalities observed on the solder joint even after 1000 cycles.